

DECLARATION OF COMPLIANCE - ELV Declaration -

NXP Semiconductors Netherlands B.V. declares that its semiconductor products (including homogeneous sub-components – pins, casing, and internal parts) are designed to be:

- ELV compliant and meet the requirements of the EU-Directive 2000/53/EC of the European Parliament of 18 September 2000 (End of Live Vehicles, ELV) and its amendments.

ELV Restricted Substance	Allowable Limit
Cadmium and its compounds	100 ppm (0.01 weight %)
Mercury and its compounds	1000 ppm (0.1 weight %)
Hexavalent chromium and its compounds	1000 ppm (0.1 weight %)
Lead and its compounds	1000 ppm (0.1 weight %)

NXP ELV compliant semiconductor devices contain no more than 0.1% lead (Pb) by weight per homogeneous material, or else the devices may contain lead (Pb) for uses allowed by the ELV Directive, as amended. NXP might use any of the following ELV exemptions for ELV compliant semiconductor devices:

ELV Exemption	RoHS Exemption Reference	ELV Exemption Description
8(e)	7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
8(a)		Lead in solders to attach electrical and electronic components to electronic circuit boards and lead in finishes on terminations of components other than electrolyte aluminum capacitors, on component pins and on electronic circuit boards.*
10(a)	7(c)-I	Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound. This exemption does not cover the use of lead in: - glass in bulbs and glaze of spark plugs, - dielectric ceramic materials of components listed under 10(b), 10(c) and 10(d).
8(g)	15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

* Applies only to vehicles type approved prior to January 1st 2016, and spare parts for these vehicles. NXP can offer lead-free termination packages for most of the devices that have terminations containing lead.

To facilitate customer requirements and to verify NXP semiconductor product compliance, NXP material content information is available [here](#) or by contacting the NXP ECO-Products team at eco-products@nxp.com.

For your convenience and immediate assistance, a spreadsheet may be downloaded from the material content link above. This document may be utilized for further processing in chemical management systems (e.g. IMDS).

In determining the ELV status of its products, NXP relies upon its suppliers' material content data certification for each homogenous material in the product(s) that they or their subcontractors provide. The signature below verifies that statements above, including but not limited to material composition data are valid and accurate to the best of our knowledge for NXP products in original sale condition. However, NXP cannot warrant that products from NXP's customers, in which such NXP products are incorporated, will in turn comply with this ELV Declaration.


 31-May-2019

Edwin Bertotti
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